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Xilinx Expands UltraScale+ Portfolio for Low Cost

Xilinx has expanded its UltraScale+ portfolio with new cost-optimized devices. They're made with TSMC's state-of-the-art integrated fan-out (InFO) packaging technology, enabling high compute density in compact form factors for intelligent edge applications.

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Ams Opens US Image Sensor R&D Center

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TAIPEI — Samsung and Taiwan Semiconductor Manufacturing Co. (TSMC) are poised to widen their IC manufacturing lead in the chip industry this year as they outspend rivals in production technology,

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TALK TO US

Bandwidth Demand Prompts Micron Transition from 3D Xpoint to CXL

Micron Technologies is exiting the once-promising 3D Xpoint non-volatile memory market, instead focusing its data center efforts on the emerging Compute Express Link interface as bandwidth requirements soar.

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Fire Destroys Part of Renesas Fab

More woes for the global automotive manufacturing industry. A serious fire at Renesas' chip making plant in Ibaraki Prefecture will, according to the company, have "a very large impact" on its ability to supply devices to the sector, as well as some other sectors.

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Xilinx Expands UltraScale+ Portfolio for Low Cost Intelligent Edge

Xilinx has expanded its UltraScale+ portfolio with new cost-optimized devices. They're made with TSMC's state-of-the-art integrated fan-out (InFO) packaging technology, enabling high compute density in compact form factors for intelligent edge applications.

In an interview with EE Times, Chetan Khona, director of the industrial, vision and healthcare group at Xilinx, said, "Compute density matters. That's why we are excited about the new InFO package, which allows us to provide substantial DMIPS per area, in an ultra-compact size."

The new Artix and Zynq UltraScale+ devices aim to address the growing need to miniaturize at the edge and endpoint, with form factors Xilinx said are 70 percent smaller than traditional chip-scale packaging.

Ams Opens US Image Sensor R&D Center

Sensor specialist Ams announced it is setting up an image sensor R&D center at Riverwood Tech Campus in Rochester, New York, to strengthen its expertise in sensor-enabled consumer imaging.

"Our focus in Rochester is on industrial AR/VR and robotics for several major US customers, but also the Ams worldwide customer base," David Sackett, senior director Research and Development, Consumer Image Sensors at Ams and site manager, told EE Times Europe.

Over the next five years, Sackett said he expects the design center in Rochester will be rolling out leading edge sensor chips using Ams's new generation of industrial imaging sensor IP. The research team will also work on developing the next generation of imaging technology that will enable future AR/VR and robotic solutions. "For these markets, we focus on small, lower power, high performance image sensors and lens modules that can be easily incorporated into all sorts of motion and wearable products like household robots such as vacuum cleaners or portable electronics for user position tracking and gesture recognition."

Samsung, TSMC are Spending to Widen IC Manufacturing Lead

TAIPEI — Samsung and Taiwan Semiconductor Manufacturing Co. (TSMC) are poised to widen their IC manufacturing lead in the chip industry this year as they outspend rivals in production technology.

The combined capital expenditures of Samsung and TSMC will reach at least $55.5 billion this year and reach a record high percentage of total semiconductor industry outlays, IC Insights said in a research bulletin this week. With no other companies able to match these huge sums, Samsung and TSMC will likely put even more distance between themselves and their competition this year with regard to advanced IC manufacturing technology

Bandwidth Demand Prompts Micron Transition from 3D Xpoint to CXL

Micron is currently in discussions with "several potential buyers" of its dedicated 3D Xpoint fab in Lehi, Utah. It hopes to complete a sale later this year, Mehrotra added. The Lehi fab led Micron's entry into the NAND market the early 2000s, later bringing Micron's version of 3D Xpoint memory technology into mass production

Micron's departure marks a turning point for 3D Xpoint technology. While Intel has doubled down on its version of the memory technology with its Optane family of persistent memory, Micron is instead hitching its wagon to the emerging CXL standard designed to ease data center bottlenecks.

Intel announced last fall it would use the proceeds of the sale of its NAND flash memory business to SK Hynix to invest in further development of Optane as the memory technology gains traction among data center operators. Observers noted that Intel has effectively been able to subsidize Optane by integrating it with server systems.

Fire Destroys Part of Renesas Fab

More woes for the global automotive manufacturing industry. A serious fire at Renesas' chip making plant in Ibaraki Prefecture will, according to the company, have "a very large impact" on its ability to supply devices to the sector, as well as some other sectors.

The fire destroyed a significant portion of the huge facility, including the 300mm line at the Naka Factory. Renesas said it was looking at the feasibility of increasing production at other facilities in order to make up for the loss of substantial volumes, and warned the stricken plant will not be operational for at least a month.

The company's CEO Hidetoshi Shibata said "we are concerned that there will be a massive impact on chip supplies; we will pursue every means possible to minimize the impact." The facility was primarily involved in making devices for the automotive sector.